









1 of 2



ThunderClad 2

Core: TU-883

Prepreg: TU-883P

ThunderClad 2 (TU-883) is a very low loss category material based on a high performance resin. This material is reinforced with regular woven E-glass and designed with very low dielectric constant and dissipation factor resin system for high speed low loss, radio frequency and wireless applications. ThunderClad 2 material is suitable for environmental protection lead free process and also compatible with FR-4 processes. ThunderClad 2 laminates also exhibit excellent moisture resistance, improved CTE, superior chemical resistance, thermal stability and CAF resistance.

Applications

- Radio frequency
- Backplane, High performance computing
- Line cards, Storage
- Servers, Telecom, Base station, Office Routers

Performance and Processing Advantages

- Excellent electrical properties
- Dielectric constant is 3.39 @ 10GHz
- Dissipation factor is 0.0045 @10GHz
- Stable and flat Dk/Df performance over frequency and temperature
- Compatible with modified FR-4 processes
- Excellent moisture resistance and Lead Free reflow process compatible
- Improved z-axis thermal expansion
- Anti-CAF capability
- Excellent through-hole and soldering reliability
- Halogen Free

Industry Approvals

- IPC-4101 Type Designation: /134
- IPC-4101/134 Validation Services QPL Certified
- UL File Number : E189572
- ANSI Grade : No-ANSI
- Flammability Rating: 94V-0
- Maximum Operating Temperature: 160°C

Standard Availability

- Thickness: 0.002"[0.05mm] to 0.062" [1.58mm], available in sheet or panel form
- Copper Foil Cladding: 1/3 to 5 oz for built-up & double sides
- Prepregs: Available in roll or panel form
- Glass Styles: 106, 1080, 3313, 2116 and other prepreg grades are available upon request







WWW.tuc.com.tw 台灣新竹廠・江苏常熟厂・广 TUC Taiwan・TUC Changshu・TUC

Delivering Value through Innovation and Dedication

2 of 2

Very Low Loss and High Thermal Reliability Laminate and Prepreg





Lead Free 👎 🙀

Typical Properties		
	Typical Values	Test Condition
Thermal		
Tg (DMA) Tg (TMA) Td (TGA)	220 °C 170 °C 420 °C	E-2/105+des
CTE x/y axis CTE z–axis α1 CTE z–axis α2 CTE z–axis	12/13 ppm/°C 35 ppm/°C 240 ppm/°C 2.5 %	Ambient to Tg Pre-Tg Post-Tg 50 to 260°C
Thermal Stress, Solder Float, 288°C	> 60 sec	Α
T-260 T-288 T-300	> 60 min > 60 min > 60 min	E-2/105+des
Flammability	94V-0	E-24/125+des
Electrical		
Permittivity (RC70%) 10GHz (SPC method) Impedance simulation DK	3.39 2.83	E-2/105
Loss Tangent (RC70%) 10GHz (SPC method)	0.0045	E-2/105
Volume Resistivity	> 10¹0 MΩ·cm	C-96/35/90
Surface Resistivity	$> 10^8~\text{M}\Omega$	C-96/35/90
Electric Strength	> 40 KV/mm	-
Dielectric Breakdown Voltage	> 50 KV	-
Mechanical		
Young's Modulus Warp Direction Fill Direction	28 GPa 26 GPa	А
Flexural Strength Lengthwise Crosswise	> 60,000 psi > 50,000 psi	A A
Peel Strength, 1.0 oz. Cu foil	4~6 lb/in	A
Water Absorption	0.08 %	E-1/105+des+D-24/23

NOTE:

- 1. Property values are for information purposes only and not intended for specification.
- 2. Any sales of these products will be governed by the terms and conditions of the agreement under which they are sold.
- ${\bf 3}.$ This product is based on a patent pending technology.

